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Product Change Notification (PCN)

Date: 14 October 2020

PCN TRACKING NO: PCN# 20201014/SM

Subject: Product Change Notification (PCN) for Alliance 8G (1Gx8) DDR3L

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Description of Change:	Product will only be offered in a new twin die 'A' die
Reason for Change	Product revision to provide continuous support to Alliance Memory's customers
	Part # change to new process technology
Traceability, Guidelines	Traceable through marketing part number
(lot, date code, markings, shipment	
Updated Datasheet	Part # has been changed and updated datasheets are posted on our website <u>https://www.alliancememory.com/wp-</u> <u>content/uploads/pdf/ddr3/AllianceMemory_DDR3L_8G_AS4C1</u> <u>G8D3LA-10BCN-BIN-BAN_Feb2019_v1.0.pdf</u>
Summary of Changes between New and Old	See table 1 Below

Table 1

Density	Organization	Alliance Part Number	Alliance New Part Number
8Gb	1Gb x 8	AS4C1G8MD3L-12BCN	AS4C1G8D3L <mark>A-10</mark> BCN
8Gb	1Gb x 8	AS4C1G8MD3L-12BCNTR	AS4C1G8D3L <mark>A-10</mark> BCNTR
NEW options added			
8Gb	1Gb x 8		AS4C1G8D3L <mark>A-10</mark> BIN
8Gb	1Gb x 8		AS4C1G8D3L <mark>A-10</mark> BINTR
8Gb	1Gb x 8		AS4C1G8D3L <mark>A-10</mark> BAN
8Gb	1Gb x 8		AS4C1G8D3LA-10BANTR

Last Time Buy Date:	31 January 2021
Last Time Ship Date:	30 June 2021
Sample Availability Date	14 October 2020
PCN Effective Date	14 October 2020

*Any orders after 31 January 2021 are Non-Cancelable/Non- Returnable and cannot be changed. Products cannot be returned in stock rotation after this date.



Dear Valued Customer:

This letter provides End–of–Life (EOL) notice of products for 8Gb DDR3L (1Gbx8 FBGA). These products will move to new 'A' die revision in Q4-2020.

The delivery deadline is 30 June 2021 with last time buy (LTB) deadline on 31 January 2021. Please note that the standard shipment dates will apply in general and extended delivery dates must be pre-arranged and accepted in writing by Alliance Memory Management.

Regarding the replacement, Alliance Memory has provided the new Dual Die Package (DDP) 25nm technology product line-up (refer to Table 1 above). The 'A' die products will provide better performance. Samples are now available for customers to start verification procedures.

Please contact your local Alliance Memory representative if you have any questions regarding this information

Yours sincerely

David Bagby

President Alliance Memory Inc.

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